

# YETDA INDUSTRY LTD.

## Technical Data Sheet

**MODEL NO : 776RGB2-CA**

Features :

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

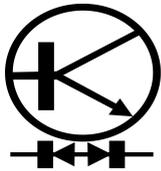
Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Red	Milky Diffused
InGaN	Green	
InGaN	Blue	

Electrical /Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit	
			Min	Typ	Max		
Spectral half bandwidth	I <sub>F</sub> =20mA	$\Delta \lambda$	R		18	nm	
			G		33		
			B		30		
Dominant wavelength	I <sub>F</sub> =20mA	$\lambda_D$	R	615	620	630	nm
			G	520	525	530	
			B	465	470	475	
Forward voltage	I <sub>F</sub> =20mA	V <sub>F</sub>	R	1.7	2.0	2.5	V
			G	2.8	3.1	3.7	
			B	2.8	3.1	3.7	
Luminous intensity	I <sub>F</sub> =20mA	I <sub>v</sub>	R	110	200	350	mcd
			G	470	485	500	
			B	70	130	220	
Viewing angle at 50% I <sub>v</sub>	I <sub>F</sub> =10mA	2θ 1/2			120	Deg	
Reverse current	V <sub>R</sub> =5V	I <sub>R</sub>			10	μA	

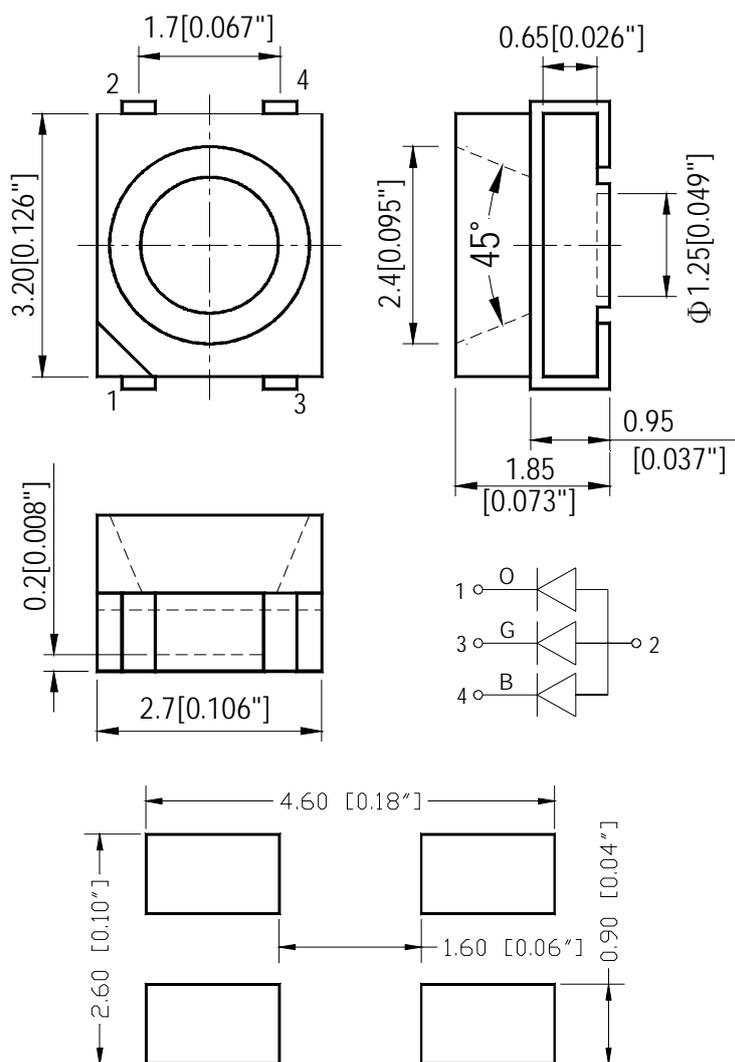


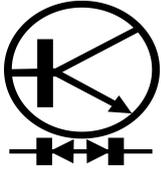
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Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Value			Unit
		R	G	B	
Power dissipation	Pd	75	111	111	mW
Forward current	IF	30			mA
Reverse voltage	VR	5			V
Operating temperature range	Top	-40 ~+80			°C
Storage temperature range	Tstg	-40 ~+85			°C
Peak pulsing current (1/8 duty f=1kHz)	IFP	125			mA

## PACKAGING DIMENSIONS (mm):

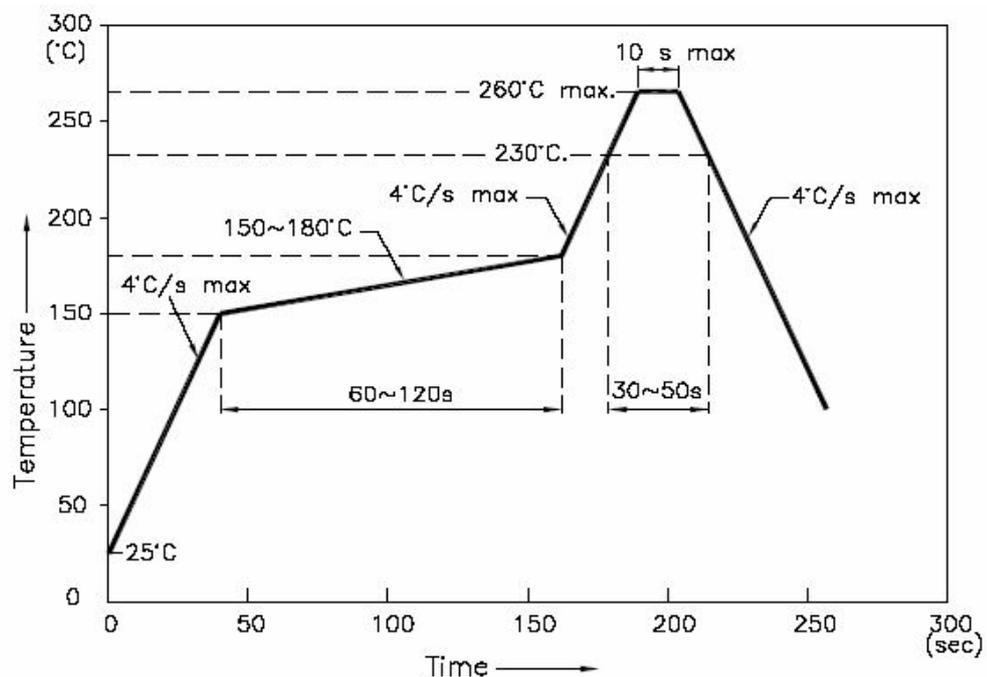




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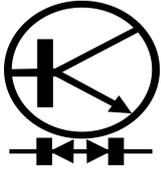
<b>Precautions For Use :</b>
<b>Over- current- proof</b>
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen )
<b>Storage</b>
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating reagent. Considering the tape life, we suggest our customers to use our products within 1.5 year ( from production date ) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.

## ■ Reflow Temp/Time



### NOTES:

1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



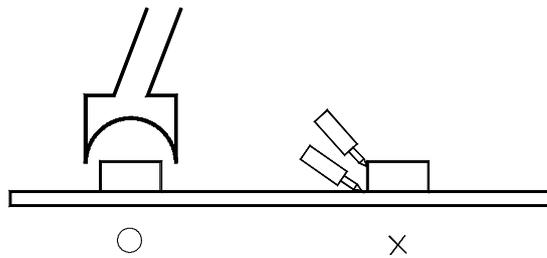
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## ■Soldering iron

Basic spec is  $\leq 5\text{sec}$  when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

## ■Rework

1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$ .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.